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What is claimed is:

1. A temperature-compensated crystal oscillator comprising:

a substrate having a circuit pattern disposed on a surface thereof and mounting electrodes disposed on a reverse side thereof and electrically connected to said circuit pattern;

circuit components mounted on the surface of said substrate and electrically connected to said circuit pattern; and

a surface-mount crystal unit having a hermetically sealed crystal blank, and mounted on the surface of said substrate and electrically connected to said circuit pattern;

said crystal blank having a cavity defined in a mounting surface thereof, at least one of said circuit components being housed in said cavity.

- 2. The temperature-compensated crystal oscillator according to claim 1, further comprising a temperature-compensating circuit, said temperature-compensating circuit compensating circuit components housed in said cavity.
- 3. The temperature-compensated crystal oscillator according to claim 2, wherein said temperature-compensating circuit is directly connected to said crystal unit, whereby the temperature-compensated crystal oscillator serves as a temperature-compensated crystal oscillator of the direct compensation type.
- 4. The temperature-compensated crystal oscillator according to claim 2, further comprising an adjusting capacitor for equalizing an oscillation frequency at a predetermined temperature to a target frequency, said adjusting capacitor

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being mounted on the surface of said substrate and disposed outside of said cavity.

- 5. The temperature-compensated crystal oscillator according to claim 1, wherein said circuit components which are disposed in said cavity comprise chip-type circuit components each having a size of 0.6 mm \times 0.3 mm.
- 6. The temperature-compensated crystal oscillator according to claim 2, further comprising a variable capacitance diode for changing an oscillation frequency depending on a control voltage supplied from an external circuit, said variable capacitance diode being mounted on the surface of said substrate and disposed outside of said cavity.